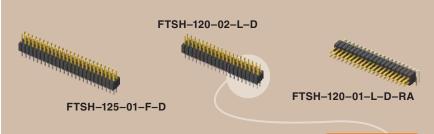




Mates with:

FLE, SFMC

FFSD. FFTP. CLP.



(1,27 mm) .050"

FTSH SERIES

THROUGH-HOLE MICRO HEADER

SPECIFICATIONS

For complete specifications see www.samtec.com?FTSH

Insulator Material: Black Liquid Crystal Polymer Terminal Material:

Terminal Material Phosphor Bronze Plating: Sn or Au over 50µ" (1,27 µm) Ni

50µ" (1,27 µm) Ni Current Rating (FTSH/CLP): 3.3 A per pin (1 pin powered per row) Operating Temp Range:

Operating Temp Range: -55°C to +125°C RoHS Compliant:

Processing: Lead-Free Solderable:

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality





Impedance matched (1,27 mm) .050" for high speed micro pitch applications (Mated with CLP Series) (2,51 mm) .099 Mates with socket strips Optional end or IDC cable shrouds and Through-hole, ejector shrouds right angle or-Surface Mount

LOCKING CLIP

For single STRIP ASSEMBLY mating cycle with the FFSD. BOARD UTUTUT Specify -LC after all option.

Lead Style -01 and 10 pins/row minimum. 5-9 pins/row available in combination with keying shroud (-K).

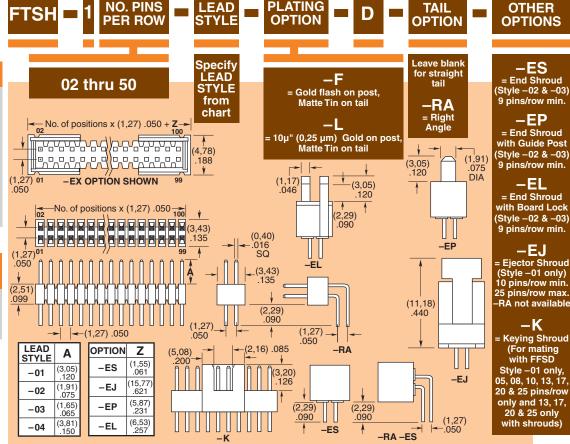
ALSO AVAILABLE (MOQ Required)

- Molded Pick & Place pads
- Other platings

Contact Samtec.

Note: See SFM/TFM for positive alignment feature.

Note: Some sizes, styles and options are non-standard, non-returnable.



Due to technical progress, all designs, specifications and components are subject to change without notice.